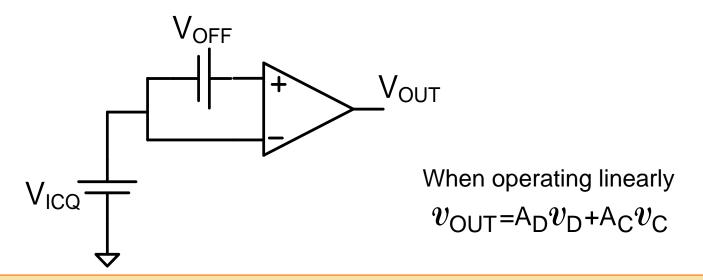
EE 435

Lecture 22

Offset Voltages



Definition: The input-referred offset voltage is the differential dc input voltage that must be applied to obtain the desired output when V_{ic} is the quiescent common-mode input voltage.

V_{OFF} is usually related to the output offset voltage by the expression

$$V_{OFF} = \frac{V_{OUTOFF}}{A_D}$$

V_{OFF} is dependent upon V_{ICO} although this dependence is usually quite weak and often not specified

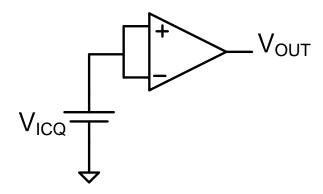
V_{OFF} almost always large enough to force op amp out of linear mode for good op amps if used open loop

Review from last lecture

Offset Voltage

Two types of offset voltage:

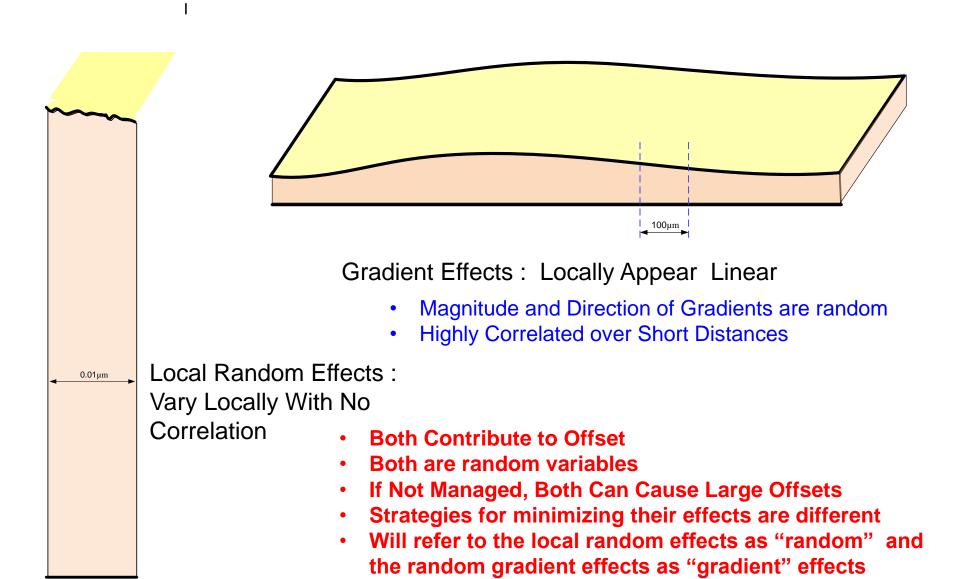
- Systematic Offset Voltage
- Random Offset Voltage



After fabrication it is impossible (difficult) to distinguish between the systematic offset and the random offset in any individual op amp

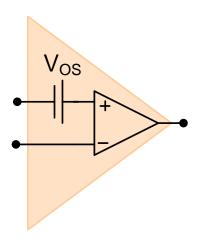
Measurements of offset voltages for a large number of devices will provide mechanism for identifying systematic offset and statistical characteristics of the random offset voltage

Gradient and Local Random Effect

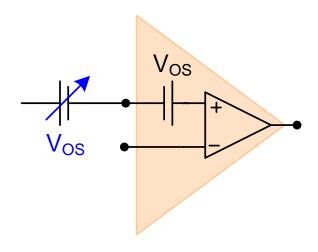


Review from last lecture

Offset Voltage



Can be modeled as a dc voltage source in series with the input



Effects can be reduced or eliminated by adding equal amplitude opposite DC signal (many ways to do this)

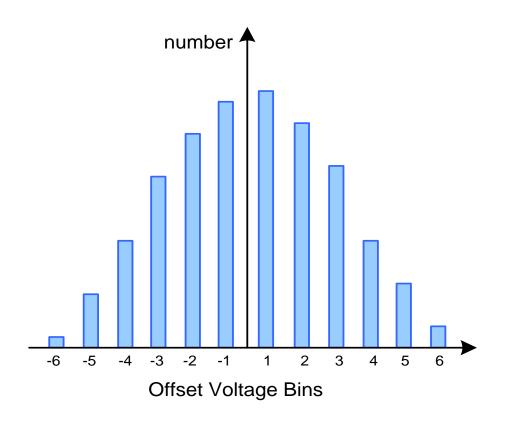
Widely used in offset-critical applications

Comes at considerable effort and expense for low offset

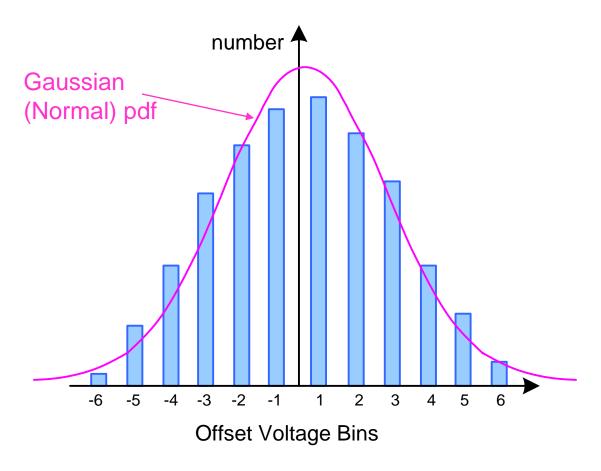
Prefer to have designer make V_{os} small in the first place

Effects of Offset Voltage

- Deviations in performance will change from one instantiation to another due to the random component of the offset
- Particularly problematic in high-gain circuits
- A major problem in many other applications
- Not of concern in many applications as well

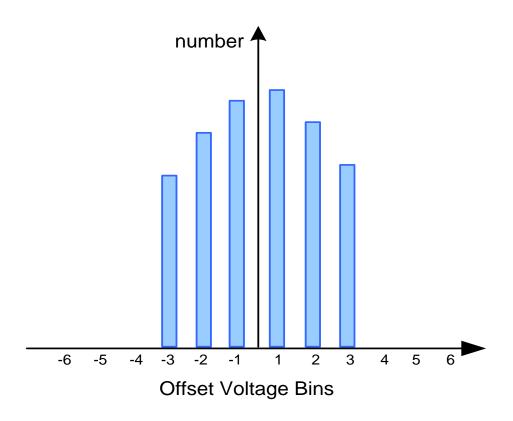


Typical histogram of random offset voltage (binned) after fabrication



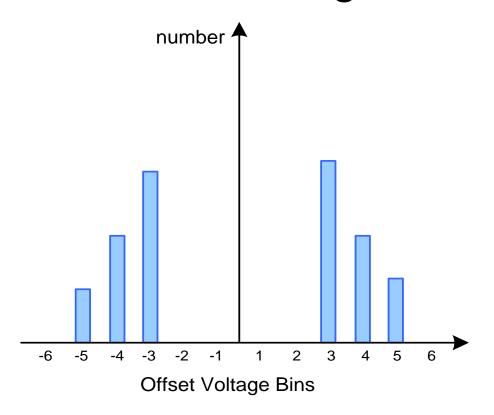
Typical histogram of offset voltage (binned) after fabrication

Mean is nearly 0 (actually the systematic offset voltage)



Typical histogram of offset voltage (binned) in shipped parts

Extreme offset parts have been sifted at test

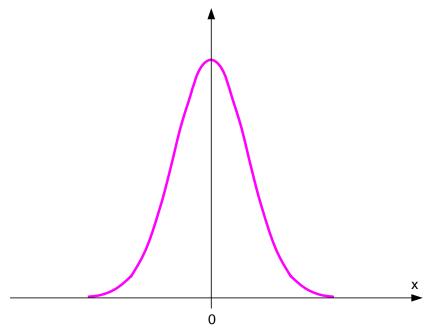


Typical histogram of offset voltage (binned) in shipped parts

Low-offset parts sometimes sold at a premium

Extreme offset parts have been sifted at test

Pdf of zero-mean Gaussian distribution

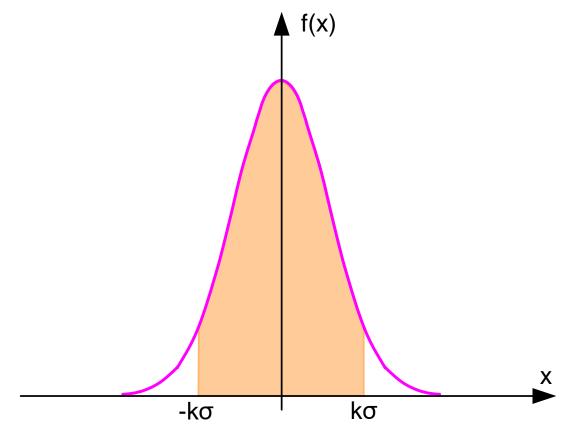


Characterized by its standard deviation σ or variance σ^2

Offset voltage often specified as the 1σ or 3σ value (though authors may neglect to indicate which)

For catalog parts, often specified as the worst-case value after sorted

Pdf of zero-mean Gaussian distribution



Percent between:

±σ 68.3% ±2σ 95.5% ±3σ 99.73%



TL082-N

www.ti.com

SNOSBW5C - APRIL 1998 - REVISED APRIL 2013

TL082 Wide Bandwidth Dual JFET Input Operational Amplifier

Check for Samples: TL082-N

FEATURES

· Internally Trimmed Offset Voltage: 15 mV

Low Input Bias Current: 50 pA

Low Input Noise Voltage: 16nV/√Hz
 Low Input Noise Current: 0.01 pA/√Hz

Wide Gain Bandwidth: 4 MHz

• High Slew Rate: 13 V/μs

Low Supply Current: 3.6 mA

High Input Impedance: 10¹²Ω

Low Total Harmonic Distortion: ≤0.02%

Low 1/f Noise Corner: 50 Hz

Fast Settling Time to 0.01%: 2 μs

DESCRIPTION

These devices are low cost, high speed, dual JFET input operational amplifiers with an internally trimmed input offset voltage (BI-FET II™ technology). They require low supply current yet maintain a large gain bandwidth product and fast slew rate. In addition, well matched high voltage JFET input devices provide very low input bias and offset currents. The TL082 is pin compatible with the standard LM1558 allowing designers to immediately upgrade the overall performance of existing LM1558 and most LM358 designs.

These amplifiers may be used in applications such as high speed integrators, fast D/A converters, sample and hold circuits and many other circuits requiring low

www.ti.com



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DC Electrical Characteristics (1)

Symbol	Davamatav	Conditions		Unite		
	Parameter	Conditions	Min	Тур	Max	Units
Vos	Input Offset ∀oltage	R _S = 10 kΩ, T _A = 25°C		5	15	m∨
		Over Temperature			20	m∨

Sifted at test if |V_{OFF}|>15mV

Guess 3σ value of trimmed but non-culled population is 15 mV



LM741

SNOSC25D - MAY 1998 - REVISED OCTOBER 2015

LM741 Operational Amplifier

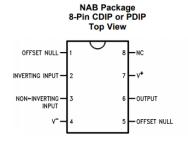
1 Features

- Overload Protection on the Input and Output
- No Latch-Up When the Common-Mode Range is Exceeded

2 Applications

3 Description

The LM741 series are general-purpose operational amplifiers which feature improved performance over industry standards like the LM709. They are direct, plug-in replacements for the 709C, LM201, MC1439, and 748 in most applications.





LM741

SNOSC25D - MAY 1998-REVISED OCTOBER 2015

www.ti.com

6.5 Electrical Characteristics. LM741(1)

PARAMETER	TEST	MIN	TYP	MAX	UNIT				
Input offset voltage	B < 10 kO	T _A = 25°C		1	5	mV			
	R _S ≤ 10 kΩ			6	mV				
Input offset voltage adjustment range	T _A = 25°C, V _S = ±20 V	$T_A = 25^{\circ}\text{C}, V_S = \pm 20 \text{ V}$				mV			



www.fairchildsemi.com

LM741 Single Operational Amplifier

Features

- · Short circuit protection
- · Excellent temperature stability
- · Internal frequency compensation
- · High Input voltage range
- · Null of offset

Description

The LM741 series are general purpose operational amplifiers. It is intended for a wide range of analog applications. The high gain and wide range of operating voltage provide superior performance in intergrator, summing amplifier, and general feedback applications.

Electrical Characteristics

(VCC = 15V, VEE = - 15V. TA = $\frac{2}{1}$ 5 °C, unless otherwise specified)

Parameter	Symbol	Conditions	LM7	Unit			
Farameter	Symbol	Conditions	Min.	Тур.	Max.	O I III	
Input Offset Voltage	VIO Rs≤10KΩ		-	2.0	6.0	mV	
Input Onset Voltage	VIO	Rs≤50Ω	-	-	-	IIIV	
Input Offset Voltage Adjustment Range	VIO(R)	V _{CC} = ±20V	-	±15	-	mV	
Input Offset Current In		-	-	20	200	nA	
Input Bias Current	IBIAS	-	-	80	500	nA	



November 1994

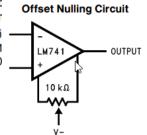
LM741 Operational Amplifier

General Description

The LM741 series are general purpose operational amplifiers which feature improved performance over industry standards like the LM709. They are direct, plug-in replacements for the 709C, LM201, MC1439 and 748 in most applications.

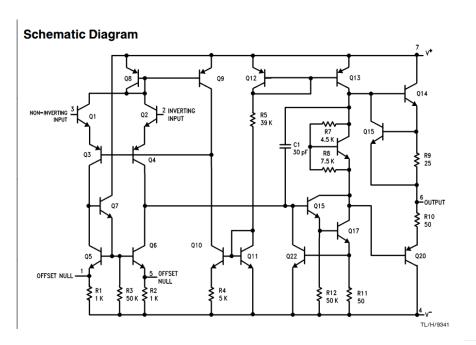
The amplifiers offer many features which make their application nearly foolproof: overload protection on the input and

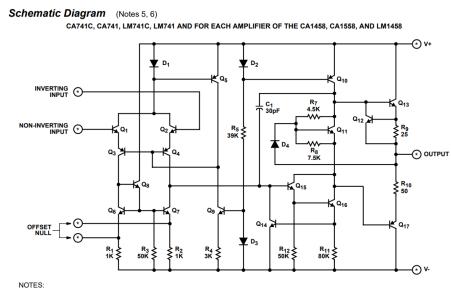
output, no latch-up when the cc ceeded, as well as freedom from The LM741C/LM741E are identi except that the LM741C/LM741 guaranteed over a 0°C to +70 stead of -55°C to +125°C.



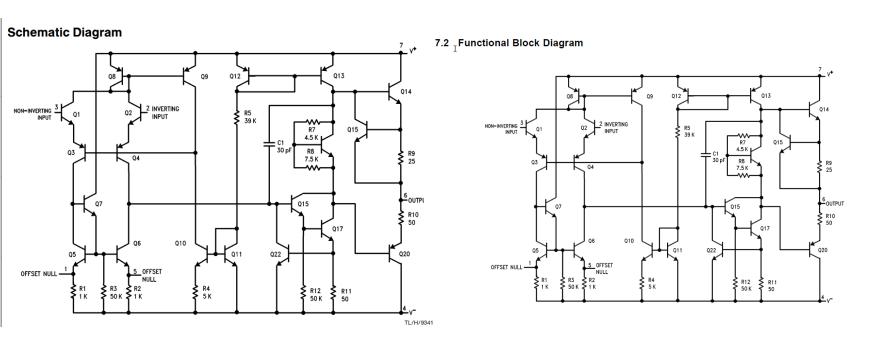
Electrical Characteristics (Note 3)

Parameter	Conditions	LM7	LM741A/LM741E		LM741			LM741C			Units
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Onits
Input Offset Voltage	$\begin{aligned} T_{A} &= 25^{\circ}C \\ R_{S} &\leq 10 \text{ k}\Omega \\ R_{S} &\leq 50\Omega \end{aligned}$		0.8	3.0		1.0	5.0		2.0	6.0	mV mV
	$\begin{split} T_{AMIN} &\leq T_A \leq T_{AMAX} \\ R_S &\leq 50\Omega \\ R_S &\leq 10 \text{ k}\Omega \end{split}$			4.0			6.0			7.5	mV mV
Average Input Offset Voltage Drift				15							μV/°C
		1	I	I	1	I	I	I	1	I	ı





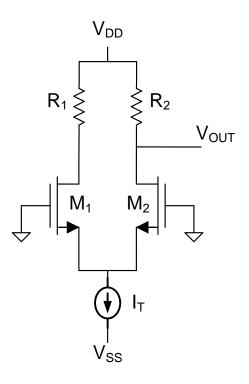
National



National

Texas Instruments

Consider as an example:



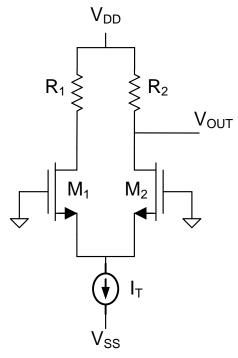
Ideally $R_1=R_2=R$, M_1 and M_2 are matched

$$V_{OUT} = V_{DD} - \left(\frac{I_T}{2}\right) R$$

Assume this is the desired output voltage

Consider as an example:

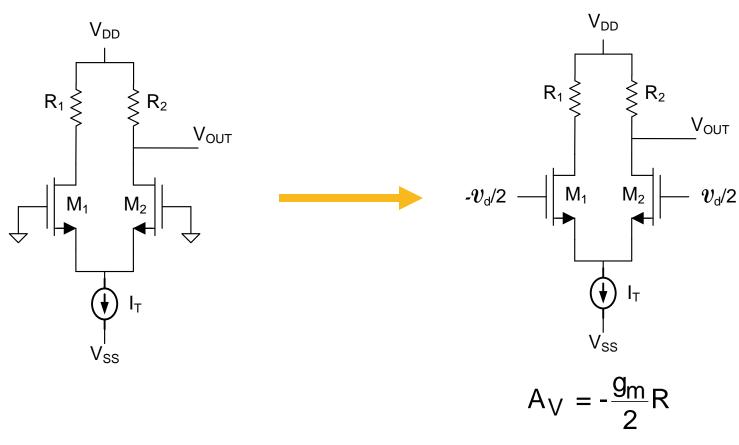
Ideally $R_1=R_2=R$ M_1 and M_2 matched



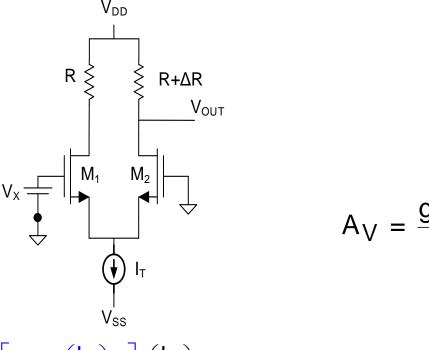
If everything ideal except $R_2=R+\Delta R$ (actually there will be mismatches between M_1 and M_2 also)

$$V_{OUT} = V_{DD} - \left(\frac{I_{T}}{2}\right) [R + \Delta R]$$
$$\Delta V_{OUT} = -\left(\frac{I_{T}}{2}\right) \Delta R$$

Consider as an example:



Determine the offset voltage – i.e. value of V_X needed to obtain desired output

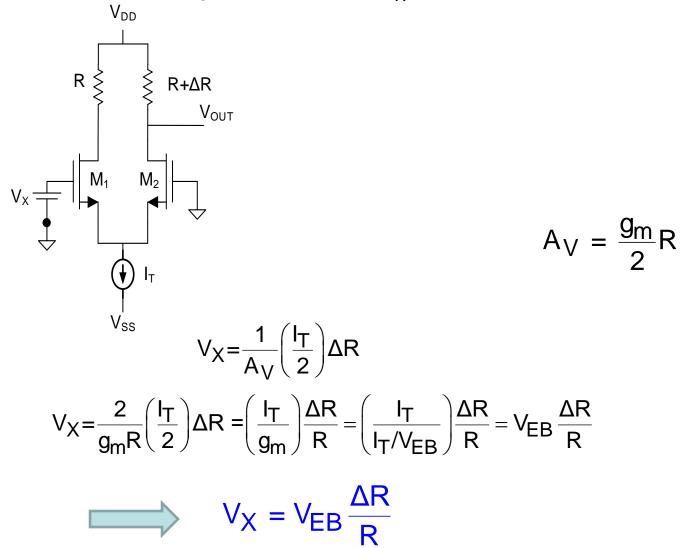


$$V_{OUT} = V_{DD} - \left(\frac{I_T}{2}\right) R - \left(\frac{I_T}{2}\right) \Delta R + A_V V_X$$

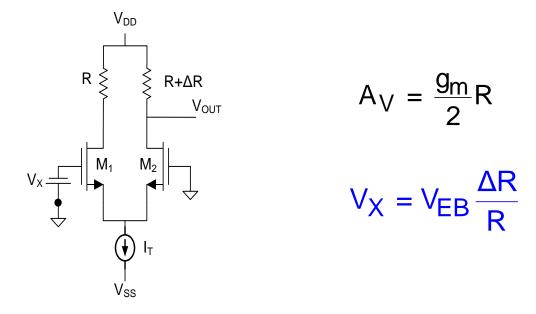
To force V_{OUT} to its desired value of $V_{OUT} = V_{DD} - \left(\frac{I_T}{2}\right)R$

$$V_X = \frac{1}{A_V} \left(\frac{I_T}{2} \right) \Delta R$$

Determine the offset voltage – i.e. value of V_X needed to obtain desired output



Determine the offset voltage – i.e. value of V_X needed to obtain desired output



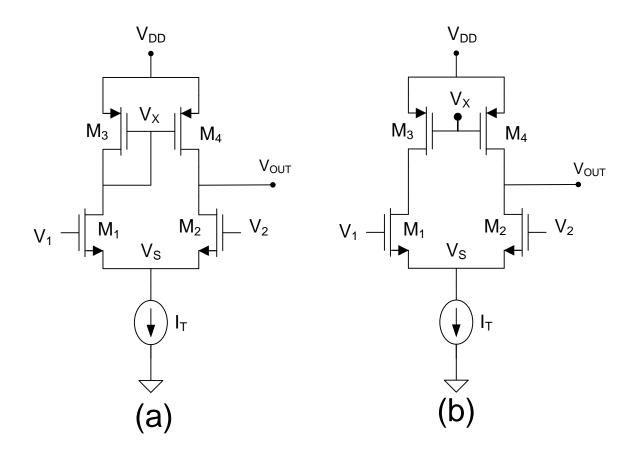
What can the designer do to reduce the offset voltage if the resistor value and statistics are fixed?

Will that affect the voltage gain?

$$A_V = \frac{g_m}{2}R = \frac{2\frac{I_T}{2V_{EB}}}{2}R = \frac{1}{2V_{EB}}I_TR$$

Not if I_T is reduced by the same amount but that will affect signal swing and GB

The random offset voltage is almost entirely that of the input stage in most op amps



- Due to random variations in process parameters and device dimensions
- Random offset is actually a random variable at the design level but deterministic after fabrication in any specific device
- Distribution naturally nearly Gaussian (could be un-naturally manipulated)

Has zero mean

Characterized by its standard deviation or variance

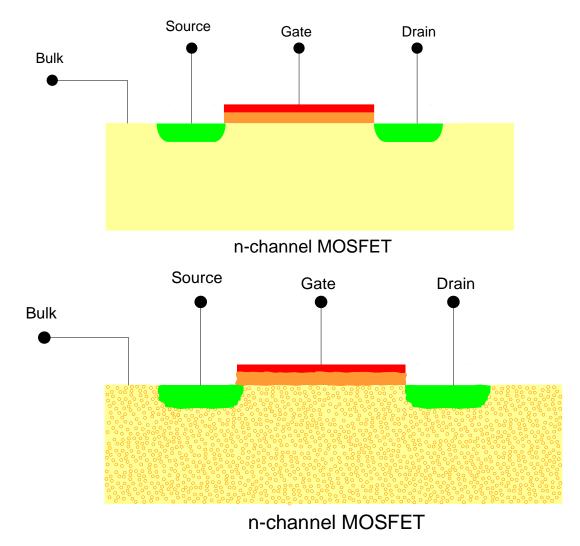
Often strongly layout dependent

Due to both local random variations and correlated gradient effects

- Will consider both effects separately
- Gradient effects usually dominate if not managed
- Good methods exist for driving gradient effects to small levels

Notation: Henceforth, the term "Random Offset" will refer to that due to local random variations and gradient effects will be considered separately

Offset Voltages due to Local Random Variations



Impurities vary randomly with position as do edges of gate, oxide and diffusions

Model and design parameters vary throughout channel and thus the corresponding equivalent lumped model parameters will vary from device to device

Model Parameter Variation

Define p to be a process parameter that varies with lateral position throughout the region defined by the channel of the transistor.

Almost Theorem:

If p(x,y) varies throughout a two-dimensional region, then

$$p_{EQ} = \frac{1}{A} \int_{A} p(x,y) dxdy$$

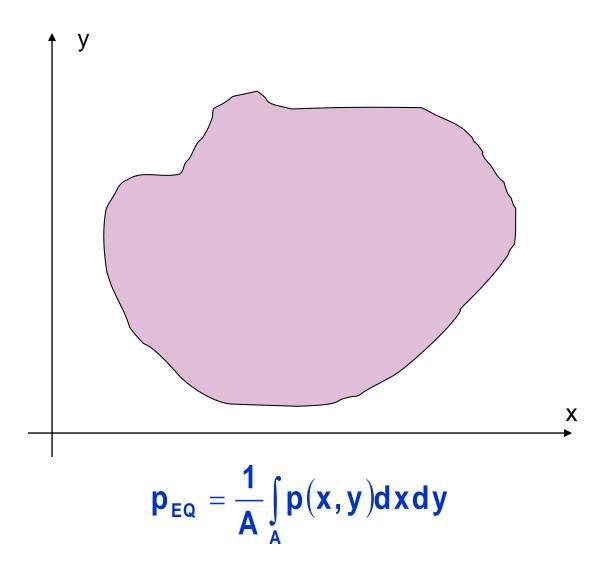
Parameters such at V_T , μ and C_{OX} vary throughout a two-dimensional region

Local random variations introduce a random component in device model parameters which are uncorrelated but for ideally matched devices they are identically distributed

e.g.
$$V_{TEQi} = V_{TN} + V_{TRi}$$

V_{TRi} and V_{TRj} due to local random variations are uncorrelated for i≠j but if ideally matched they are identically distributed

Model Parameter Variation



The random offset associated with <u>local random variations</u> is due to mismatches in the four transistors, dominantly mismatches in the parameters $\{V_T, \mu, C_{OX}, W \text{ and } L\}$

The relative mismatch effects become more pronounced as devices become smaller

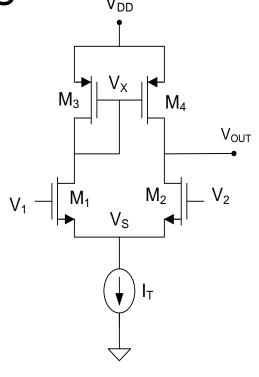
$$V_{Ti} = V_{TN} + V_{TRi}$$

$$C_{OXi} = C_{OXN} + C_{OXR}$$

$$\mu_i = \mu_N + \mu_{Ri}$$

$$W_i = W_N + W_{Ri}$$

$$L_i = L_N + L_{Ri}$$



Each design and model parameter is comprised of a nominal part and a random component

It will be assumed that the random parts of each model parameter are uncorrelated but if ideally matched are identically distributed

(actually some small correlation in "model" parameters but will neglect in this course)

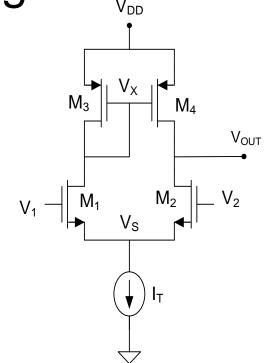
$$V_{Ti} = V_{TN} + V_{TRi}$$

$$C_{OXi} = C_{OXN} + C_{OXRi}$$

$$\mu_{i} = \mu_{N} + \mu_{Ri}$$

$$W_{i} = W_{N} + W_{Ri}$$

$$L_{i} = L_{N} + L_{Ri}$$



For each device, the device model is often expressed as

$$I_{Di} = \frac{\left(\mu_{N} + \mu_{Ri}\right)\left(C_{OXN} + C_{OXRi}\right)\left(W_{N} + W_{Ri}\right)}{2\left(L_{N} + L_{Ri}\right)} \left(V_{GSi} - (V_{TN} + V_{TRi})\right)^{2} \left(1 + \left(\lambda_{N} + \lambda_{Ri}\right)\left[V_{DS}\right]\right)$$

Because of the random components of the parameters in every device, matching from the left-half circuit to the right half-circuit is not perfect

This mismatch introduces an offset voltage which is a random variable

For this 4-transistor op amp, there are 24 uncorrelated random variables

From a straightforward but tedious analysis (involving the 24 random variables) it follows that:

$$\sigma_{V_{OS}}^{2} = 2 \left[\frac{A_{VTO\,n}^{2} + \frac{\mu_{p}}{\mu_{n}} \frac{L_{n}}{W_{n}L_{n}} A_{VTO\,p}^{2} + \frac{V_{EB\,n}^{2}}{4} \left[\frac{1}{W_{n}L_{n}} A_{\mu_{n}}^{2} + \frac{1}{W_{p}L_{p}} A_{\mu_{p}}^{2} + A_{COX}^{2} \left[\frac{1}{W_{n}L_{n}} + \frac{1}{W_{p}L_{p}} \right] \right] + A_{W}^{2} \left[\frac{1}{L_{n}W_{n}^{2}} + \frac{1}{L_{p}W_{p}^{2}} \right] \right]$$

where the terms A_{VT0} , A_{μ} , A_{COX} , A_{L} , and A_{W} are process parameters

Typical values for matching model parameters:

$$A_{VT0} \cong \begin{cases} 21 m V \raisebox{-.4ex}{$\scriptscriptstyle \bullet$} \mu & \text{ (n-ch)} \\ 25 m V \raisebox{-.4ex}{$\scriptscriptstyle \bullet$} \mu & \text{ (p-ch)} \end{cases}$$

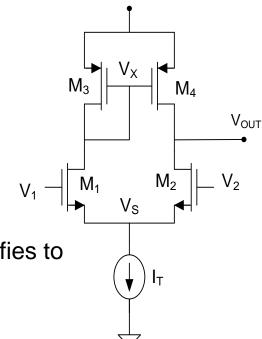
$$\sqrt{A_{\mu}^2\!+\!A_{C_{OX}}^2} \cong \begin{cases} .016\mu & \text{(n-ch)} \\ .023\mu & \text{(p-ch)} \end{cases}$$

$$A_L = A_W \cong 0.017 \mu^{\frac{3}{2}}$$

Usually the A_{VT0} terms are dominant, thus the variance simplifies to

$$\sigma_{V_{OS}}^{2} \cong 2 \left[\frac{A_{VTO\,n}^{2}}{W_{n} L_{n}} + \frac{\mu_{p}}{\mu_{n}} \frac{L_{n}}{W_{n} L_{p}^{2}} A_{VTO\,p}^{2} \right]$$

(Remember this is due to local random variations)



$$\sigma_{V_{OS}}^2 \cong 2 \left[\frac{A_{VTO\,n}^2}{W_n L_n} + \frac{\mu_p}{\mu_n} \frac{L_n}{W_n L_p^2} A_{VTO\,p}^2 \right]$$

This expression has somewhat peculiar coefficients. The first term on the right is dependent upon the reciprocal of the area of the n-channel device but the corresponding coefficient on the second term on the right appears to depend upon the dimensions of both the n-channel and p-channel devices. But this can be rewritten as

$$\sigma_{V_{OS}}^{2} \cong 2 \left[\frac{A_{VTO\,n}^{2}}{W_{n} L_{n}} + \left(\frac{V_{EB\,n}}{V_{EB\,p}} \right)^{2} \frac{A_{VTO\,p}^{2}}{W_{p} L_{p}} \right]$$

The dependence of the variance on the area of the n-channel and p-channel devices is more apparent when written in this form.

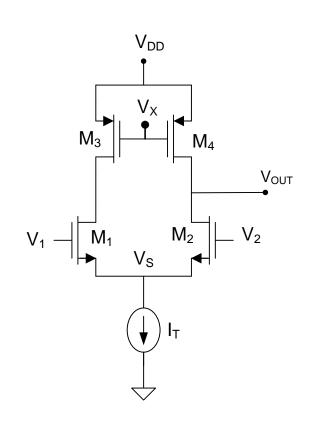
Correspondingly:

$$\sigma_{v_{os}}^{2} = 2 \left[\frac{A_{vTOn}^{2}}{W_{n}L_{n}} + \frac{\mu_{p}}{\mu_{n}} \frac{L_{n}}{W_{n}L_{p}^{2}} A_{vTOp}^{2} + \frac{V_{EBn}^{2}}{4} \left(\frac{1}{W_{n}L_{n}} A_{\mu_{n}}^{2} + \frac{1}{W_{p}L_{p}} A_{\mu_{p}}^{2} + A_{COX}^{2} \left[\frac{1}{W_{n}L_{n}} + \frac{1}{W_{p}L_{p}} \right] + A_{w}^{2} \left[\frac{1}{L_{n}W_{n}^{2}} + \frac{1}{L_{p}W_{p}^{2}} \right] \right) \right]$$

which again simplifies to

$$\sigma_{V_{OS}}^{2} \cong 2 \left[\frac{A_{VTO\,n}^{2}}{W_{n} L_{n}} + \frac{\mu_{p}}{\mu_{n}} \frac{L_{n}}{W_{n} L_{p}^{2}} A_{VTO\,p}^{2} \right]$$

Note these offset voltage expressions are identical!



Example: Determine the 3σ value of the input offset voltage for The MOS differential amplifier if

- a) M₁ and M₃ are minimum-sized and
- b) the area of M_1 and M_3 are 100 times minimum size (with $L_n = L_p$)

$$\sigma_{V_{OS}}^{2} \cong 2 \left[\frac{A_{VTO\;n}^{2}}{W_{n}\;L_{n}} + \frac{\mu_{p}}{\mu_{n}} \frac{L_{n}}{W_{n}\;L_{p}^{2}} A_{VTO\;p}^{2} \right]$$

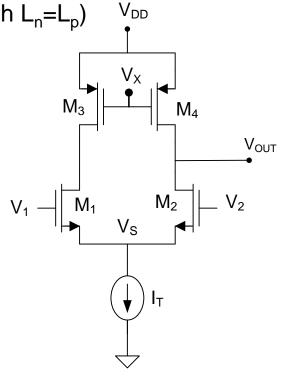
$$\sigma_{V_{OS}}^{2} \cong \frac{2}{W_{n} L_{n}} \left[A_{VTO}^{2} n^{+} \frac{\mu_{p}}{\mu_{n}} A_{VTOp}^{2} \right]$$

a)
$$\sigma_{V_{OS}}^{2} \cong \frac{2}{(0.5\mu)^{2}} \left[.021^{2} + \frac{1}{3}.025^{2} \right]$$

$$\sigma_{V_{OS}} \cong 72\text{mV}$$

$$3 \sigma_{V_{OS}} \cong 216\text{mV}$$

Note this is a very large offset voltage!



Example: Determine the 3σ value of the input offset voltage for the MOS differential amplifier due to local random variations if:

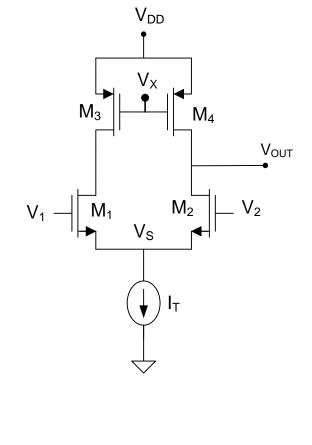
- a) M₁ and M₃ are minimum-sized and
- b) the area of M₁ and M₃ are 100 times minimum size

$$\sigma_{V_{OS}}^{2} \cong 2 \left[\frac{A_{VTO\,n}^{2} + \frac{\mu_{p}}{\mu_{n}} \frac{L_{n}}{W_{n} L_{p}^{2}} A_{VTO\,p}^{2} \right]$$

$$\sigma_{V_{OS}}^{2} \cong \frac{2}{W_{n} L_{n}} \left[A_{VTO\,n}^{2} + \frac{\mu_{p}}{\mu_{n}} A_{VTO\,p}^{2} \right]$$
b)
$$\sigma_{V_{OS}}^{2} \cong \frac{2}{100(0.5\mu)^{2}} \left[.021^{2} + \frac{1}{3}.025^{2} \right]$$

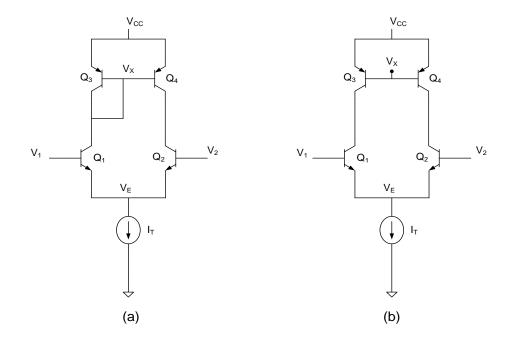
$$\sigma_{V_{OS}} \cong 7.2 \text{mV}$$

$$3 \sigma_{V_{OS}} \cong 21.6 \text{mV}$$



Note this is much lower but still a large offset voltage!

The area of M₁ and M₃ need to be very large to achieve a low offset voltage



It can be shown that

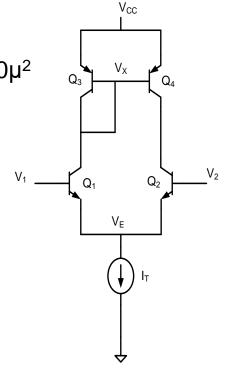
$$\sigma_{V_{OS}}^2 \cong 2V_t^2 \left| \frac{A_{Jn}^2}{A_{En}} + \frac{A_{Jp}^2}{A_{Ep}} \right|$$

where very approximately

$$A_{Jn} = A_{Jp} = 0.1\mu$$

Example: Determine the 3σ value of the offset voltage of a the bipolar input stage due to local random variations if $A_{E1}=A_{E3}=10\mu^2$

$$\begin{split} \sigma_{V_{OS}}^2 &\cong 2 \text{V}_{\text{t}}^2 \left[\frac{\text{A}_{Jn}^2}{\text{A}_{En}} + \frac{\text{A}_{Jp}^2}{\text{A}_{Ep}} \right] \\ \sigma_{V_{OS}} &\cong \sqrt{2} \text{V}_{\text{t}} \text{ A}_{\text{J}} \frac{\sqrt{2}}{\sqrt{\text{A}_{E}}} \\ \sigma_{V_{OS}} &\cong 2 \bullet 25 \text{mV} \bullet 0.1 \mu \bullet \frac{1}{\sqrt{10 \mu^2}} = 1.6 \text{mV} \\ 3\sigma_{V_{OS}} &\cong 4.7 \text{mV} \end{split}$$



Note this value is much smaller than that for the MOS input structure!

Typical offset voltages:

MOS - 5mV to 50MV

BJT - 0.5mV to 5mV

These can be scaled with extreme device dimensions

Often more practical to include offset-compensation circuitry

- Due to random variations in process parameters and device dimensions
- Random offset is actually a random variable at the design level but deterministic after fabrication in any specific device
- Distribution naturally nearly Gaussian (could be un-naturally manipulated)

Has zero mean

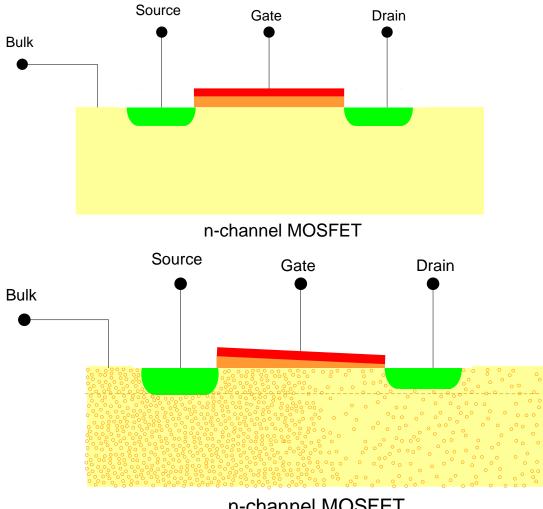
Characterized by its standard deviation or variance

Often strongly layout dependent

Due to both local random variations and correlated gradient effects

- Will consider both effects separately
- Gradient effects usually dominate if not managed
- Good methods exist for driving gradient effects to small levels

Offset Voltages due to Gradients



n-channel MOSFET

Impurity density or layer thicknesses vary linearly through the channel

Model and design parameters vary throughout channel and thus the corresponding equivalent lumped model parameters will vary from device to device

Model Parameter Variation

Define p to be a process parameter that varies with lateral position throughout the region defined by the channel of the transistor.

Almost Theorem:

If p(x,y) varies throughout a two-dimensional region, then

$$p_{EQ} = \frac{1}{A} \int_{A} p(x,y) dxdy$$

Parameters such at V_T , μ and C_{OX} vary throughout a two-dimensional region Gradients

Local random variations introduce a random component in device model parameters which are uncorrelated for neighborhood devices but for ideally matched devices they correlated

are identically distributed

e.g.
$$V_{TEQi} = V_{TN} + V_{TRi}$$

gradients correlated V_{TRi} and V_{TRj} due to local random variations are uncerrelated for i≠j but if ideally matched they are identically distributed

Define p to be a process parameter that varies <u>linearly</u> with lateral position throughout the region defined by the channel of the transistor.

Almost Theorem:

If p(x,y) varies linearly throughout a two-dimensional region, then

$$p_{EQ} = \frac{1}{A} \int_{A} p(x,y) dxdy$$

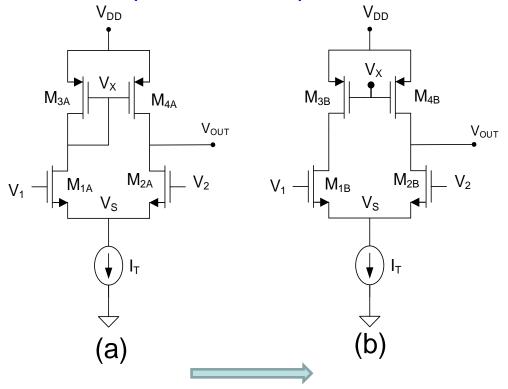
Gradient effects cause parameters such at V_T , μ and C_{OX} to vary approximately linearly throughout a two-dimensional region

The direction and magnitude of gradients are random variables but are correlated and identical for closely-placed devices

Source of Random Offset Voltages

The random offset voltage is almost entirely that of the input stage in most op amps

Assume schematic representative of placement of devices in layout



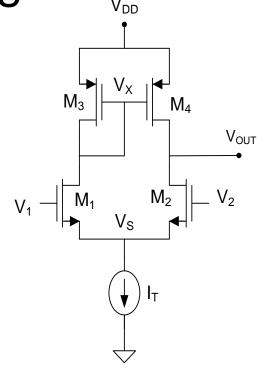
If threshold gradient in this direction and local random variations are neglected $V_{TH2A} = V_{TH1A} + \alpha d$

 α is the magnitude of the gradient d is the distance between M_{1A} and M_{2A}

The random offset associated with local random variations is due to missmatches in the four transistors, dominantly missmatches in the parameters $\{V_T, \mu, C_{OX}, W \text{ and } L\}$

Gradient effects and local random variations are both present and additive

$$\begin{split} &V_{Ti} = V_{TN} + V_{TRi} + V_{TGi} \\ &C_{OXi} = C_{OXN} + C_{OXRi} + C_{OXGi} \\ &\mu_i = \mu_N + \mu_{Ri} + \mu_{Gi} \\ &W_i = W_N + W_{ri} + W_{Gi} \\ &L_i = L_N + L_{ri} + L_{Gi} \end{split}$$



Each design and model parameter is comprised of a nominal part and a random component

The local random parts of each model parameter are uncorrelated but if ideally matched are identically distributed and the gradient parts for closely placed devices are correlated

Gradients are uncorrelated with local random variations

Recall:

Model Parameter Variations

Define p to be a process parameter that varies with lateral position throughout the region defined by the channel of the transistor.

Almost Theorem:

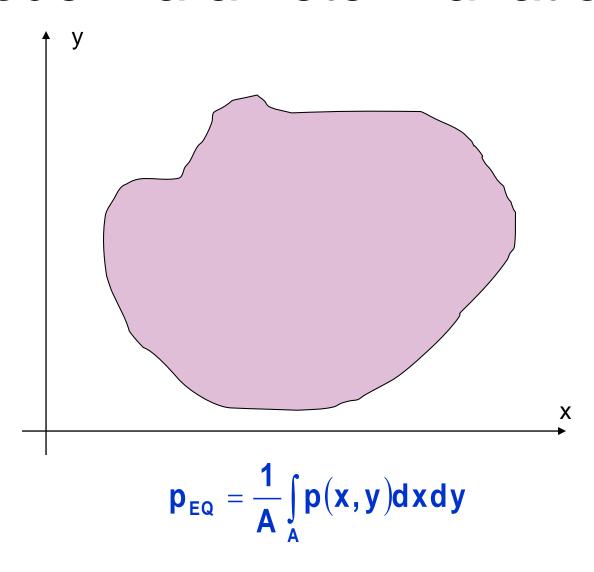
If p(x,y) varies throughout a two-dimensional region, then

$$p_{EQ} = \frac{1}{A} \int_{A} p(x,y) dxdy$$

Parameters such at V_T , μ and C_{OX} vary throughout a two-dimensional region

Recall:

Model Parameter Variations

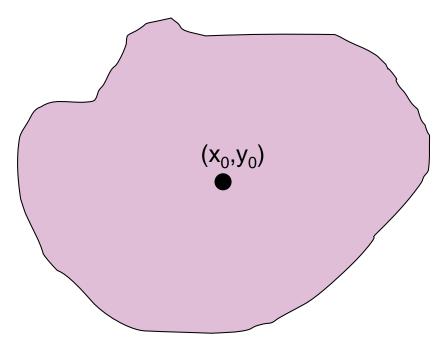


Almost Theorem:

If p(x,y) varies linearly throughout a two-dimensional region, then $p_{EQ}=p(x_0,y_0)$ where x_0,y_0 is the geometric centroid to the region.

If a parameter varies linearly throughout a two-dimensional region, it is said to have a linear gradient.

Many parameters have a dominantly linear gradient over rather small regions but large enough to encompass layouts where devices are ideally matched



 (x_0,y_0) is geometric centroid

$$p_{EQ} = \frac{1}{A} \int_{A} p(x,y) dxdy$$

If $\rho(x,y)$ varies linearly in any direction, then the theorem states

$$p_{EQ} = \frac{1}{A} \int_{A} p(x,y) dxdy = p(x_0,y_0)$$

Definition: A layout of two devices is termed a common-centroid layout if both devices have the same geometric centroid

Almost Theorem:

If p(x,y) varies linearly throughout a two-dimensional region, then if two devices have the same centroid, the linear-variable parameters are matched!

Note: This is true independent of the magnitude and direction of the gradient!

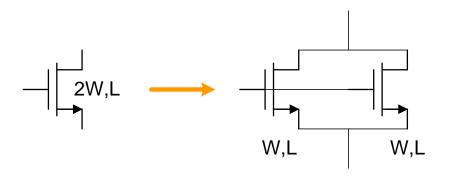
Almost Theorem:

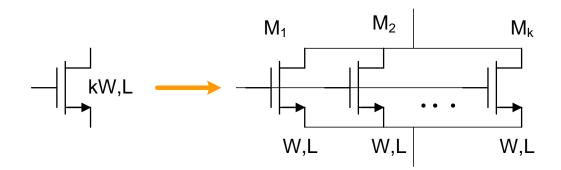
If a common-centroid layout is used for the matching-critical part of an operational amplifier, the linear part of the linear-variable parameters (e.g. V_{TH} , μ , C_{OX}) will introduce no offset voltage!

Common-centroid layouts almost always used for matching-critical components to eliminate linear gradients of critical parameters!

But local random variations will still affect matching even if gradient effects are eliminated

Recall parallel combinations of transistors equivalent to a single transistor of appropriate W,L

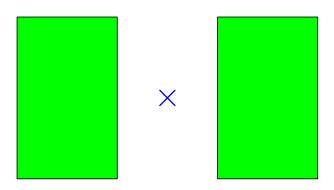


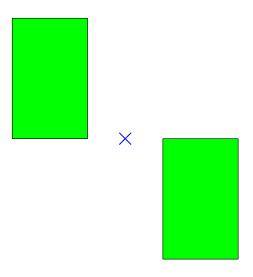


A single device is comprised of a parallel interconnection of smaller devices is termed a segmented structure

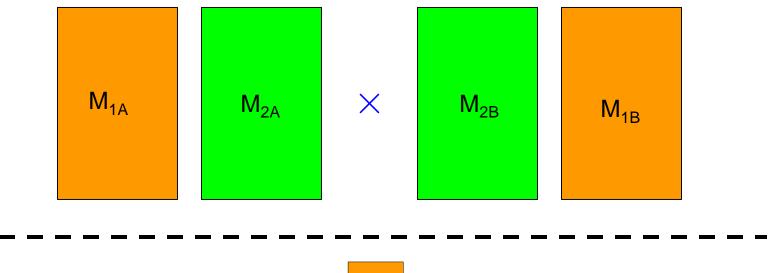
Centroids of Segmented Geometries

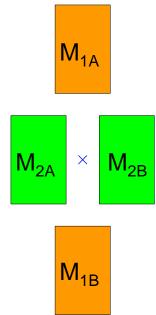
X Denotes Geometric Centroid





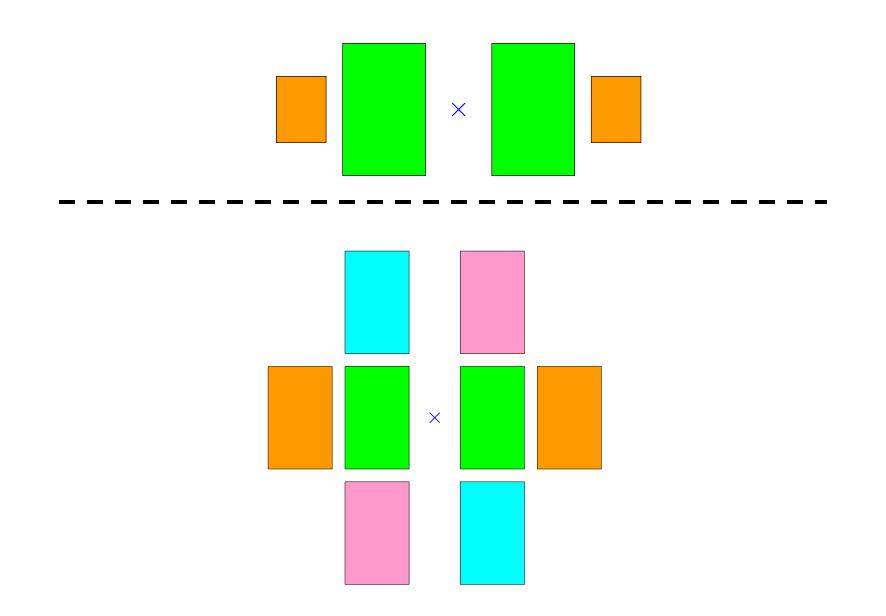
Common Centroid of Multiple Segmented Geometries

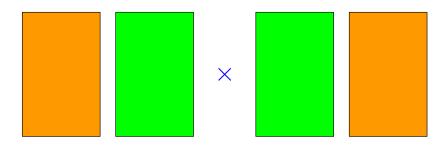




If these are layouts of gates of two transistors with two segments, M₁ and M₂ have common centroids. They are thus termed common-centroid layouts

Common Centroid of Multiple Segmented Geometries





Common centroid layouts widely (almost always) used where matching of devices or components is critical because these layouts will cancel all first-order gradient effects

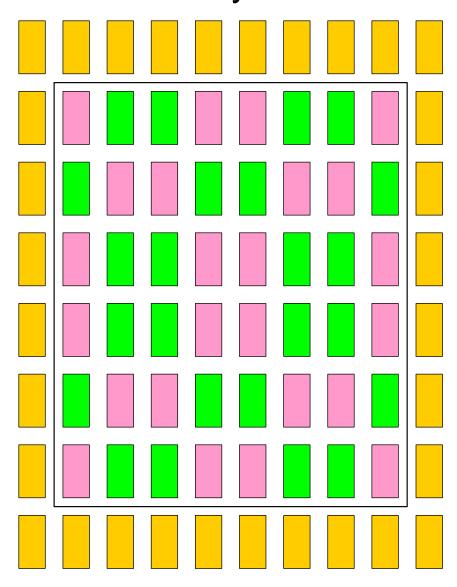
Applies to resistors, capacitors, transistors and other components

Always orient all devices in the same way

Keep common centroid for interconnects, diffusions, and all features

Often dummy devices placed on periphery to improve matching!

Common Centroid Layout Surrounded by Dummy Devices





Stay Safe and Stay Healthy!

End of Lecture 22